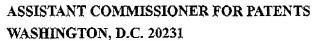
03-28-01

PATENT

Docket No. <u>JCLA7157</u> Date: 03/27/01

Page 1



ATTENTION: APPLICATION BRANCH

Sir:

Transmitted herewith for filing is the patent application of

Inventors: Terng-Yin Hsu; Chen-Yi Lee; Fan-Ming Kuo

For: METHOD OF OPERATING A MATCHED FILTER OF A PAM WITH VARIABLE

LENGTHS

Enclosed are:

- (×) Specification 7 pages.
- (×) 2 Sheets of drawings
- () Recordation Form Cover sheet with ___ pages assignment.
- () A certified copy of Taiwan Patent Application No. _____ dated_____
- () SIGNED declaration and power of attorney.
- (×) Return Prepaid postcard.

CLAIMS AS FILED						
FOR	NUMBE	NUMBER		BER	RATE	FEE
	FILED		EXTRA			
Basic Fee					\$710	\$ 710
Total Claims	3	-20	=0	×	\$18	\$0
Independent Claims	2	-3	=0	×	\$80	\$0
If application contains any multiple dependent claim (s), then add					\$270	\$ 0
TOTAL FILING FEE						\$ 710

- (×) A check in the amount of \$710 cover the filing fee is enclosed.
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JCLA7157 Docket No.

Terng-Yin Hsu; Chen-Yi Lee; Fan-Ming Kuo Applicant(s)

METHOD OF OPERATING A MATCHED For

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